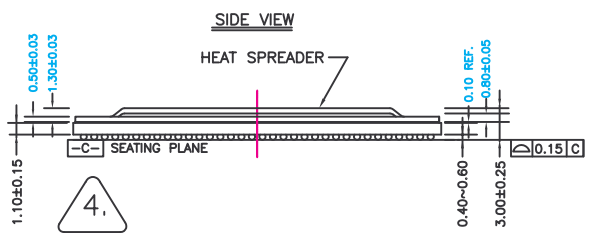
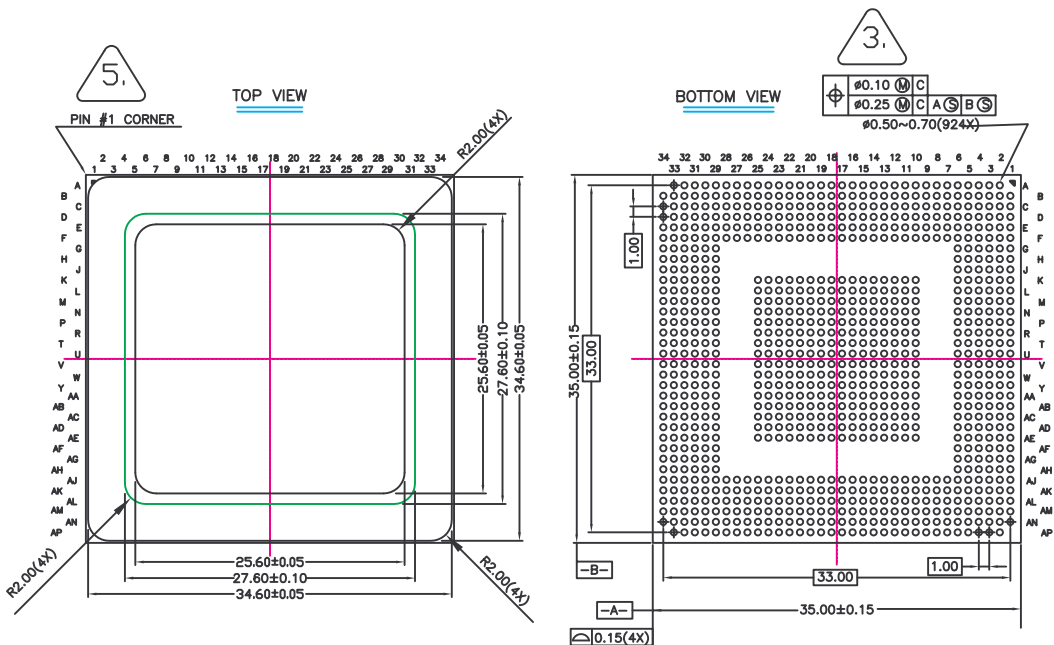



REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	02/08	Eden
A	Modified Heat Slug	08/08	Eden



NOTES:

1. DIMENSION IS MM.
 2. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM AND BALL DIA IS 0.60MM
3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. A1 BALL PAD CORNER I.D.

SIGNATURE		DATE		 <p>TITLE MARKETING OUTLINE DRAWING 35MM X 35MM X 3.00MM, 924 BALLS, HFBGA W/HEAT SINK, 6 LAYER 1.00 MM PITCH</p>			
DOC. CONTROL:							
ENGR. MGR:							
MFG. ENGR:				SIZE	FSCM NO.	PART NO.	REV.
CHECKED BY: Bill Harmon		08/08		A		21-0372	B
DRAWN BY: Eden Chen		08/08		SCALE	N/A	SHEET	1 of 1